

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6691224

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
FENG ZHOU	04/29/2021
HIROSHI UKEGAWA	04/29/2021
ERCAN MEHMET DEDE	04/29/2021
RECEIVING PARTY DATA	
Name:	TOYOTA MOTOR ENGINEERING & MANUFACTURING NORTH AMERICA, INC.
Street Address:	6565 HEADQUARTERS DRIVE W1-3C
City:	PLANO
State/Country:	TEXAS
Postal Code:	75024
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17307405
CORRESPONDENCE DATA	
Fax Number:	(513)977-8141
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	513-977-8200
Email:	Hanna.Coleman@dinsmore.com
Correspondent Name:	DINSMORE & SHOHL LLP
Address Line 1:	255 E. 5TH STREET
Address Line 2:	SUITE 1900
Address Line 4:	CINCINNATI, OHIO 45202
ATTORNEY DOCKET NUMBER:	22562-6071 / 2020-581
NAME OF SUBMITTER:	GREGORY T. WUENNENBERG
SIGNATURE:	/Gregory T. Wuennenberg/
DATE SIGNED:	05/04/2021
Total Attachments: 2	
source=ExecAssignment#page1.tif	
source=ExecAssignment#page2.tif	

ASSIGNMENT

WHEREAS, we, **Feng Zhou**, of 2794 Ashcombe Dr., Ann Arbor, MI 48105, and **Hiroshi Ukegawa**, of 58575 Winnowing Cir. S., South Lyon, MI 48178, and **Ercan Mehmet Dede**, of 2227 Placid Way, Ann Arbor, MI 48105, hereinafter the *ASSIGNOR(S)*, invented certain new and useful **CHIP-ON-CHIP POWER DEVICES EMBEDDED IN PCB AND COOLING SYSTEMS INCORPORATING THE SAME** for which we executed an application for a United States Patent and for which said application for United States Patent was filed on May 4, 2021, under

☒ Patent Application Serial No. 17/307,405

☒ Attorney Docket No. 22562-6071 / 2020-581 / IP-A- 4958 ;

WHEREAS, the *ASSIGNOR(S)* hereby authorize(s) and request(s) the attorney(s) and/or agent(s) empowered to act on **Toyota Motor Engineering & Manufacturing North America, Inc.**'s behalf in the aforementioned application, to insert above the filing date and application number of said application, when known;

WHEREAS, **Toyota Motor Engineering & Manufacturing North America, Inc.**, a corporation of the State of Kentucky, with a place of business at 6565 Headquarters Drive W1-3C, Plano, Texas 75024, hereinafter called the *ASSIGNEE*, is desirous of acquiring *ASSIGNOR(S)* entire right, title and interest in and to said application and the inventions therein disclosed and any Letters Patent that may issue thereon;

AND, WHEREAS, it is the intent of the *ASSIGNOR(S)* to assign all rights to the above referenced application to the *ASSIGNEE*, including, but not limited to, all substantive rights in the above-referenced application as well as the right to claim priority, the right to be granted a patent in any and all countries and Regional Patent Offices, including, without limitation, the PCT Contracting States;

NOW, THEREFORE, for good and valuable consideration, receipt whereof is hereby acknowledged, *ASSIGNOR(S)* hereby sell, assign and transfer unto said *ASSIGNEE*, its successors and assigns, the entire right, title and interest, including the right to claim priority in and to said application, the inventions therein disclosed, and any improvements thereon, and in any and all Letters Patent that may be granted therefor in the United States and its territorial possessions and in any and all countries and Regional Patent Offices, including, without limitation, the PCT Contracting States, and in and to any and all divisions, continuations, substitutions, renewals, re-examinations, extensions and reissues thereof;

ASSIGNOR(S) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions, and in any and all countries and Regional Patent Offices, including, without limitation, the PCT Contracting States, to issue, when granted, any Letters Patent thereon, and any and all divisions, continuations, substitutions, renewals, re-examinations, extensions and reissues thereof, to said *ASSIGNEE*, its successors and assigns, as the assignee of the entire right title and interest in and to the same, for the sole use and behalf of the *ASSIGNEE* and the *ASSIGNEE*'s successors and assigns, to the full end of the term for which the Letters Patent may be granted, including the term of any and all divisions, continuations, substitutions, renewals, re-examinations, extensions and reissues thereof, as fully and entirely as the same would have been held by the *ASSIGNOR(S)* had this assignment not been made;

ASSIGNOR(S) hereby authorize said *ASSIGNEE*, its successors and assigns, to file in its own name applications for patent in foreign countries in connection with the inventions hereby transferred, under the International Convention claiming the priority of said United States application or otherwise, and to secure in its own name the Letters Patent issued thereon, including any and all divisions, continuations, substitutions, renewals, re-examinations, extensions and reissues thereof; and

ASSIGNOR(S) hereby agree that, upon request, *ASSIGNOR(S)* will sign all papers, and make all rightful oaths, and do all acts which said *ASSIGNEE*, its successors or assigns, may consider necessary in connection with said United States application, and in connection with any other United States application or foreign applications that may be filed in connection with said inventions, and with any improvements thereon, and in connection with any Letters Patent issued thereon, including any and all divisions, continuations, substitutions, renewals, re-examinations, extensions and reissues thereof.

ASSIGNOR(S):

By: */Feng Zhou/*
Feng Zhou
4/29/2021
Date: _____

By: */Hiroshi Ukegawa/*
Hiroshi Ukegawa
4/29/2021
Date: _____

By: */Ercan Mehmet Dede/*
Ercan Mehmet Dede
4/29/2021
Date: _____

17413537v1